

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

Claim 1 (canceled).

Claim 2 (previously presented): A laminated electronic component according to claim 5, wherein only one of the insulating layers is interposed between said additional conductor film and said external conductor film.

Claim 3 (canceled).

Claim 4 (previously presented): A laminated electronic component comprising:
a laminated block including a plurality of electrically insulating layers and an internal conductor film disposed between the insulating layers laminated together in a thickness direction of said laminated block;

an external conductor film disposed on an exposed surface of said laminated block; and

an additional conductor film which is at the same electric potential as said external conductor film and which is arranged along a specific interface between the insulating layers such that said additional conductor film faces said external conductor film; wherein

said insulating layers are formed of ceramic material; and

the thickness of the insulating layer between said additional conductor film and said external conductor film ranges from about 25 μm to about 150 μm .

Claim 5 (currently amended): A laminated electronic component comprising:

a laminated block including a plurality of electrically insulating layers and an internal conductor film disposed between the insulating layers laminated together in a thickness direction of said laminated block;

an external conductor film disposed on an exposed surface of said laminated block; and

an additional conductor film which is at the same electric potential as said external conductor film and which is arranged along a specific interface between the insulating layers such that said additional conductor film faces said external conductor film; wherein

said insulating layers are formed of ceramic material;

the area of said additional conductor film is greater than or equivalent to the area of said external conductor film, and is arranged such that said additional conductor film covers said external conductor film therein when viewed from above or below; ~~and~~

the external conductor film defines one of a die bonding surface and a land for mounting; and

the thickness of the insulating layer between said additional conductor film and said external conductor film ranges from about 10 μm to about 150 μm .

Claim 6 (previously presented): A laminated electronic component according to claim 5, wherein said additional conductor film and said external conductor film are electrically connected to each other through a via-hole conductor.

Claim 7 (previously presented): A laminated electronic component comprising:
a laminated block including a plurality of electrically insulating layers and an internal conductor film disposed between the insulating layers laminated together in a thickness direction of said laminated block;

an external conductor film disposed on an exposed surface of said laminated block; and

an additional conductor film which is at the same electric potential as said external conductor film and which is arranged along a specific interface between the insulating layers such that said additional conductor film faces said external conductor film; wherein

said insulating layers are formed of ceramic material; and

said additional conductor film and said external conductor film are electrically connected to each other through a conductor disposed on an outer surface of said laminated block.

Claim 8 (previously presented): A laminated electronic component according to claim 5, wherein a DC bias is applied between said external conductor film and said internal conductor film.

Claim 9 (previously presented): A laminated electronic component according to claim 5, wherein said laminated block includes a first main surface and a second main surface facing the first main surface, and said external conductor film is disposed on at least one of the first and second main surfaces.

Claim 10 (original): A laminated electronic component according to claim 9, further comprising a chip component mounted on at least one of the first and second main surfaces, wherein said external conductor film is arranged to establish an electrical connection with said chip component.

Claim 11 (original): A laminated electronic component according to claim 10, wherein said chip component is one of a capacitor, an inductor, a resistor, a diode, an integrated circuit, a memory device, a SAW filter and a quartz oscillator.

Claim 12 (original): A laminated electronic component according to claim 9, wherein said external conductor film is arranged to establish an electrical connection with a board on which said laminated electronic component is mounted.

Claim 13 (previously presented): A laminated electronic component comprising:
a laminated block including a plurality of electrically insulating layers and an internal conductor film disposed between the insulating layers laminated together in a thickness direction of said laminated block;

an external conductor film disposed on an exposed surface of said laminated block; and

an additional conductor film which is at the same electric potential as said external conductor film and which is arranged along a specific interface between the insulating layers such that said additional conductor film faces said external conductor film; wherein

a cavity having an opening positioned on at least one of main surfaces of said laminated block is provided in said laminated block, and said external conductor film is disposed on the bottom surface of the cavity; and

said insulating layers are formed of ceramic material.

Claim 14 (previously presented): A laminated electronic component according to claim 13, further comprising a chip component housed in the cavity, wherein said external conductor film defines a die bonding surface for bonding the chip component.

Claim 15 (previously presented): A laminated electronic component according to claim 13, wherein said additional conductor film and said external conductor film are electrically connected to each other through a via-hole conductor, and the via-hole conductor is positioned in an area outside the bottom surface of the cavity.

Claim 16 (canceled).

Claim 17 (previously presented): A laminated electronic component according to claim 5, wherein said internal conductor film defines at least one of a capacitor, a ground potential and a wiring for connection to an electronic component.

Claim 18 (previously presented): A laminated electronic component according to claim 5, further comprising a plurality of internal conductors and via-hole conductors which are arranged to provide at least one of wiring patterns, capacitors, inductors, delay lines, and filters.

Claim 19 (previously presented): A laminated electronic component according to claim 18, wherein the plurality of internal conductors and via hole conductors are disposed within said laminated block.

Claim 20 (previously presented): A laminated electronic component according to claim 5, further comprising resistor films for defining resistors.

Claim 21 (previously presented): A laminated electronic component according to claim 20, wherein said resistor films are disposed within said laminated block.